



# **N-Channel Power MOSFET**

650V, 10A, 0.8Ω

#### **FEATURES**

- 100% UIS and Rg tested
- · Advanced planar process
- Compliant to RoHS Directive 2011/65/EU and in accordance to WEEE 2002/96/EC
- Halogen-free according to IEC 61249-2-21

## **APPLICATIONS**

- AC/DC LED Lighting
- Power Supply

KEY PERFORMANCE PARAMETERS				
PARAMETER VALUE UNIT				
$V_{DS}$	650	V		
R <sub>DS(on)</sub> (max)	0.8	Ω		
$Q_g$	39.6	nC		









ABSOLUTE MAXIMUM RATINGS (T <sub>A</sub> = 25°C unless otherwise noted)				
PARAMETER		SYMBOL	Limit	UNIT
Drain-Source Voltage		V <sub>DS</sub>	650	V
Gate-Source Voltage		V <sub>GS</sub>	±30	V
Continuous Drain Current (Note 1)	T <sub>C</sub> = 25°C		10	۸
	$T_C = 100$ °C	I <sub>D</sub>	6.3	A
Pulsed Drain Current (Note 2)		I <sub>DM</sub>	40	А
Total Power Dissipation @ T <sub>C</sub> = 25°C		P <sub>DTOT</sub>	56.8	W
Single Pulse Avalanche Energy (Note 3)		E <sub>AS</sub>	435	mJ
Single Pulse Avalanche Current (Note 3)		I <sub>AS</sub>	6.6	А
Operating Junction and Storage Temp	perature Range	T <sub>J</sub> , T <sub>STG</sub>	- 55 to +150	°C

THERMAL PERFORMANCE				
PARAMETER	SYMBOL	Limit	UNIT	
Junction to Case Thermal Resistance	R <sub>eJC</sub>	2.2	°C/W	
Junction to Ambient Thermal Resistance	R <sub>OJA</sub>	62	°C/W	

**Thermal Performance Note:**  $R_{\Theta JA}$  is the sum of the junction-to-case and case-to-ambient thermal resistances. The case-thermal reference is defined at the solder mounting surface of the drain pins.  $R_{\Theta JA}$  is guaranteed by design while  $R_{\Theta CA}$  is determined by the user's board design.



<b>ELECTRICAL SPECIFICATIONS</b> (T <sub>A</sub> = 25°C unless otherwise noted)						
PARAMETER	CONDITIONS	SYMBOL	MIN	TYP	MAX	UNIT
Static		<u>.</u>				
Drain-Source Breakdown Voltage	$V_{GS} = 0V, I_D = 250\mu A$	BV <sub>DSS</sub>	650			V
Gate Threshold Voltage	$V_{DS} = V_{GS}, I_{D} = 250 \mu A$	V <sub>GS(TH)</sub>	2.5	3	3.8	V
Gate Body Leakage	$V_{GS} = \pm 30V, V_{DS} = 0V$	I <sub>GSS</sub>			±100	nA
Zero Gate Voltage Drain Current	$V_{DS} = 650 V, V_{GS} = 0 V$	I <sub>DSS</sub>			1	μΑ
Drain-Source On-State Resistance (Note 4)	$V_{GS} = 10V, I_D = 2.5A$	R <sub>DS(on)</sub>		0.59	0.8	Ω
Dynamic (Note 5)					l	
Total Gate Charge		Qg		39.6		
Gate-Source Charge	$V_{DS} = 520V, I_D = 5A,$ $V_{GS} = 10V$	$Q_{gs}$		8.1		nC
Gate-Drain Charge		$Q_{gd}$		12.5		
Input Capacitance	$V_{DS} = 50V, V_{GS} = 0V,$	C <sub>iss</sub>		1863		
Output Capacitance		C <sub>oss</sub>		108		pF
Reverse Transfer Capacitance	f = 1.0MHz	C <sub>rss</sub>		9		
Gate Resistance		R <sub>g</sub>		1.3	2.6	Ω
Switching (Note 6)		<u>.</u>				
Turn-On Delay Time		t <sub>d(on)</sub>		11		
Turn-On Rise Time	$V_{DD} = 325V, R_G = 5\Omega,$	t <sub>r</sub>		20		
Turn-Off Delay Time	$I_D = 5A, V_{GS} = 10V$	t <sub>d(off)</sub>		36		ns
Turn-Off Fall Time		t <sub>f</sub>		23		
Source-Drain Diode						
Body-Diode Continuous Forward Current		Is			10	Α
Body-Diode Pulsed Current		I <sub>SM</sub>			40	Α
Forward Voltage (Note 4)	I <sub>S</sub> = 5A, V <sub>GS</sub> = 0V	$V_{SD}$			1.2	V
Reverse Recovery Time	I <sub>S</sub> = 5A	t <sub>rr</sub>		253		ns
Reverse Recovery Charge	$dI_F/dt = 100A/\mu s$	Q <sub>rr</sub>		2.5		μC

## Notes:

- 1. Current limited by package
- 2. Pulse width limited by the maximum junction temperature
- 3. L = 20mH,  $I_{AS} = 6.6A$ ,  $V_{DD} = 50V$ ,  $R_G = 25\Omega$ , Starting  $T_J = 25^{\circ}C$
- 4. Pulse test: PW  $\leq$  300 $\mu$ s, duty cycle  $\leq$  2%
- 5. For DESIGN AID ONLY, not subject to production testing.
- 6. Switching time is essentially independent of operating temperature.

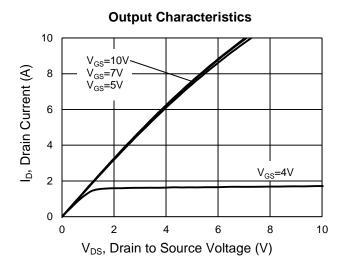
# **ORDERING INFORMATION**

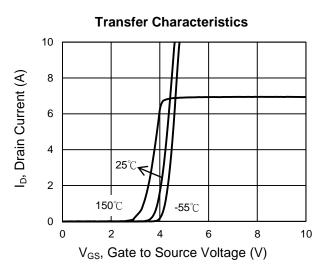
PART NO.	PACKAGE	PACKING
TSM10ND65CI C0G	ITO-220	50pcs / Tube

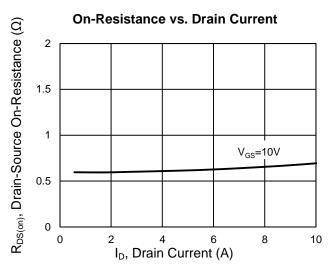


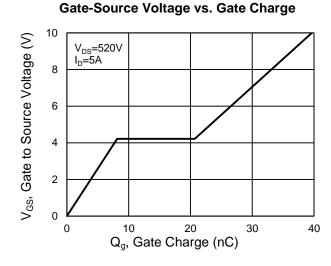
## **CHARACTERISTICS CURVES**

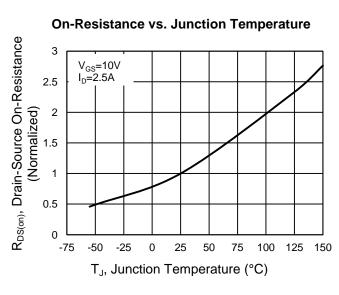
(T<sub>C</sub> = 25°C unless otherwise noted)

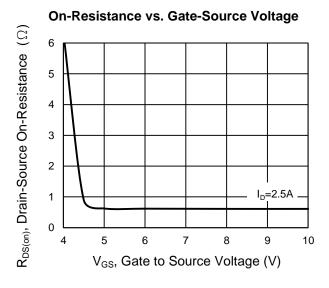












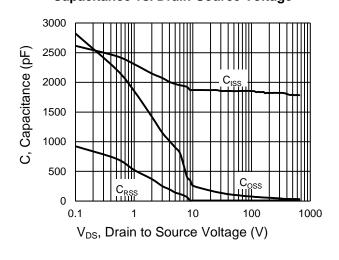
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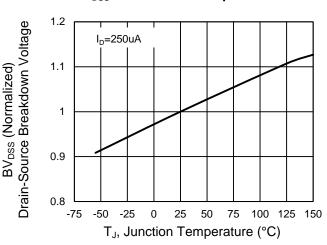
## **CHARACTERISTICS CURVES**

 $(T_C = 25^{\circ}C \text{ unless otherwise noted})$ 

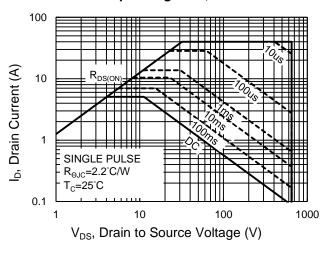
# Capacitance vs. Drain-Source Voltage



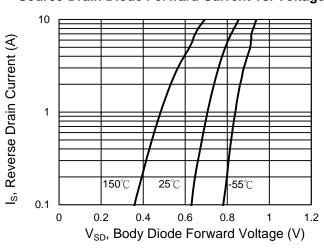
#### BV<sub>DSS</sub> vs. Junction Temperature

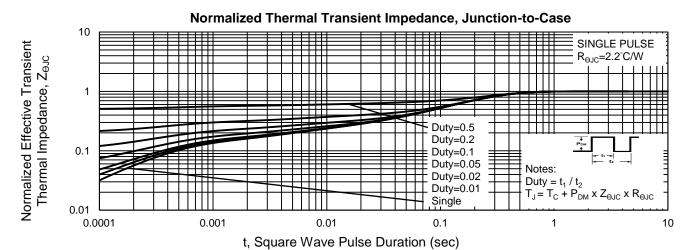


#### Maximum Safe Operating Area, Junction-to-Case



# Source-Drain Diode Forward Current vs. Voltage

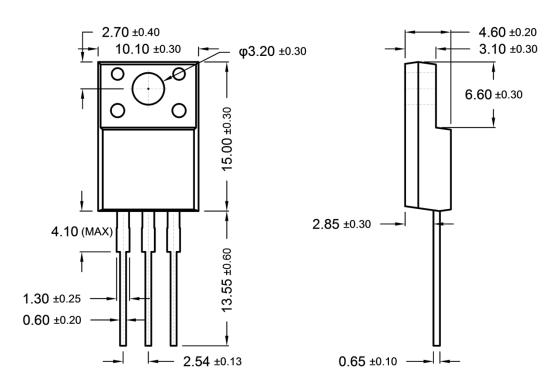






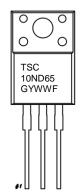
# PACKAGE OUTLINE DIMENSIONS (Unit: Millimeters)

# **ITO-220**



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# **MARKING DIAGRAM**



**G** = Halogen Free

Y = Year Code

WW = Week Code (01~52)

F = Factory Code



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